MPI Corporation.

(6223.TT)

2012 Taiwan, Technology & Beyond Conference
The information herein contains forward-looking statements. We have based these forward-looking statements on our current expectations and projections about future events. Although we believe that these expectations and projections are reasonable, such forward-looking statements are inherently subject to risks, uncertainties and assumptions about us, including, among other things: the intensely competitive Semi-conductor, and LED industries and markets; Cyclical nature of the semiconductor industry; Risks associated with global business activities; General economic and political conditions; Other risks identified in our annual report for the year ended February 29th, 2012. All financial figures discussed herein are prepared pursuant to ROC GAAP on an un-audited unconsolidated basis. All audited figures will be publicly announced upon the completion of our audited process.
Company at a Glance

- **Founded**: July, 25, 1995
- **Paid-in Capital**: NTD$ 786M (2011.12.31-the latest)
- **Employees**: 878 (2011.12.31)
Business Portfolio

Probe Card
- 4Q 2010: 32%
- 1Q 2011: 30%
- 2Q 2011: 32%
- 3Q 2011: 36%
- 4Q 2011: 51%

Leda
- 4Q 2010: 36%
- 1Q 2011: 67%
- 2Q 2011: 66%
- 3Q 2011: 63%
- 4Q 2011: 49%

Solar
- 4Q 2010: 2%
- 1Q 2011: 2%
- 2Q 2011: 1%
- 3Q 2011: 0%
- 4Q 2011: 5%
LED
The Process of LED Manufacturing

1. **Wafer**
   - Kyocera,
   - Monochrystal,
   - Rubicon, Sumitomo

2. **Gas**
   - Sumitomo,
   - Dow Chemical

3. **MOCVD**
   - Aixtron
   - Veeco

4. **Laser Dicers**
   - Disco

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**Test**
- Towa,
- ASM Pacific,
- MPI Corporation

**Packaging**
- Stanley Electric,
- Everlight

**Final Test**
- Towa,
- ASM Pacific
- MPI Corporation

**End Product**
- Sharp, GE, Osram
- Gree, Philips
- Toshiba, Panasonic

*Source: Deutsche Bank*
WW MOCVD Installation

WW MOCVD Installation Volume

Source: LEDinside
LED ASP Trend

LED’s ASP Dramatically Plummeted in 2011

Source: LEDinside
LED Turnkey Solution for Probing and Sorting in Chip level and package level

Chip Level
- Prober
- Sorter

Package Level
- Handler
- Tapping

2 in 1 (Prober + Sorter)
- Reduce spacing demand for capex
- Reduce workforce
- Process improvement
2 in 1 Machine (Prober + Sorter)

Specifications

- **Wafer Size**: Max 6” (150mm) after expansion (for GR6/GR5)
- **Bin Area**: 60mm x 60mm
- **Pattern Recognition System**
  - PR System: 256 grey levels
  - Resolution: 640 pixels x 480 pixels
  - PR Accuracy: ± 0.025 mil (Die size 64mil x 48mil)
  - Angle Range: ± 15°

- **Dimension**
  - Wide: 1400mm
  - Height: 1650mm
  - (not included signal-tower)
  - Length: 1530mm
  - Weight: 1000Kg

- **Loader**
  - Wafer Cassette: 2 (8 rings for GR6/GR5)
  - Bin Cassette: 6 (25 bins with a single Cassette)

- **Features**
  - Reduce spacing demand for capex
  - Reduce workforce
  - Process improvement
PT-380 SORTING

Specifications

- Applicable device: Chip type LED
- Loader: Parts feeder
- Number of test station: 1 (2: option)
- Test method: Side or top surface contact
- Cycle time: Max 0.15 sec/pcs (UPH24K) (Including 90msec test time)
- Number of bin: 256 bulk bins
- Vacuum source: Vacuum pump
- Size: W1,160 x H1,458 x D788(mm)
**Auto Taping Machine**

*PT-350 TAPING*

**Specifications**

- Applicable device: Each chip type devices
- Embossed Carrier tape width: 8 (mm)
- Supply reel/ Accept reel: Max.Ø700/ Max. Ø330
- Loader: Parts feeder with hopper
- Seal method: Heat press reciprocating method
- Cycle time: 0.09 sec/pcs (666pcs/min)
- Vacuum source: Vacuum pump
- Vision: Vision  Align and check device
- Size: W870 x H1,352 x D681(mm)
Geography & Product Mix

by Geography

Taiwan, 14, 15%
China, 78, 85%

Country, PC, %

by Product

<table>
<thead>
<tr>
<th>Season</th>
<th>Sorter</th>
<th>Prboer</th>
</tr>
</thead>
<tbody>
<tr>
<td>3Q-10(S)</td>
<td>286</td>
<td>499</td>
</tr>
<tr>
<td>4Q-10(S)</td>
<td>112</td>
<td>571</td>
</tr>
<tr>
<td>1Q-11(S)</td>
<td>48</td>
<td>387</td>
</tr>
<tr>
<td>2Q-11(S)</td>
<td>87</td>
<td>313</td>
</tr>
<tr>
<td>3Q-11(S)</td>
<td>34</td>
<td>388</td>
</tr>
<tr>
<td>4Q-11(S)</td>
<td>16</td>
<td>76</td>
</tr>
</tbody>
</table>

Season
LEDA Client-Distribution (2011 YTD)

1. ANHUI SANAN OPTOELECTRONICS CO., LTD
2. ELEC-TECH PHOTOELECTRIC TECHNOLOGY (DALIAN) CO., LTD
3. EVERVISION ELECTRONICS LTD
4. SHANXI FEIHONG MICRONANO PHOTOELECTRONICS SCIENCE & TECHNOLOGY CO., LTD
5. JIANGSU XINGUANGLIAN TECHNOLOGY CO., LTD
LED Chip Market Development Distribution

- The LED epi wafer & chip field, more than 70 LED makers in the LED epi wafer & chip field and the production value reached 625 million USD.
Probe Card
Major Customers

- Design Houses
  - Novatek
  - Himax
  - Marvell
  - OmniVision
  - NVIDIA
  - Qritech

- Foundries
  - TSMC
  - UMC
  - GlobalFoundries

- Testing Houses
  - KYEC
  - ChipBond
  - ChipMOS
  - IST
### Income Statement

<table>
<thead>
<tr>
<th></th>
<th>NT$1,000</th>
<th>Q3' 2011</th>
<th>Q3' 2010</th>
<th>YoY(%)</th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>Net Sales</strong></td>
<td>3,081,069</td>
<td>100%</td>
<td>2,429,119</td>
<td>100%</td>
</tr>
<tr>
<td><strong>Cost of Goods Sold</strong></td>
<td>1,770,321</td>
<td>57.5%</td>
<td>1,415,934</td>
<td>58.3%</td>
</tr>
<tr>
<td><strong>Gross Profit</strong></td>
<td>1,310,748</td>
<td>42.5%</td>
<td>1,013,185</td>
<td>41.7%</td>
</tr>
<tr>
<td><strong>Operating Expense</strong></td>
<td>756,145</td>
<td>24.5%</td>
<td>548,833</td>
<td>22.6%</td>
</tr>
<tr>
<td><strong>Operating Income</strong></td>
<td>553,712</td>
<td>18.0%</td>
<td>460,914</td>
<td>19.0%</td>
</tr>
<tr>
<td><strong>Investment Income &amp; Others</strong></td>
<td>92,202</td>
<td>3.0%</td>
<td>94,319</td>
<td>3.9%</td>
</tr>
<tr>
<td><strong>Net Income (before tax)</strong></td>
<td>645,914</td>
<td>21.0%</td>
<td>555,233</td>
<td>22.9%</td>
</tr>
<tr>
<td><strong>EPS (before tax)</strong></td>
<td>8.15</td>
<td></td>
<td>7.09</td>
<td></td>
</tr>
</tbody>
</table>

#### Graph

The graph displays the net sales (NT$ 1,000) for each month from January to December for the years 2008 to 2011. The net sales data is represented in different colors for each year:
- **2008**: Light blue
- **2009**: Green
- **2010**: Blue
- **2011**: Red
### Balance Sheet Highlight

<table>
<thead>
<tr>
<th>Amount: NT$ Million</th>
<th>Q3’ 2011</th>
<th>Q3’ 2010</th>
</tr>
</thead>
<tbody>
<tr>
<td>Cash and Cash Equivalents</td>
<td>863</td>
<td>933</td>
</tr>
<tr>
<td></td>
<td>23%</td>
<td>14%</td>
</tr>
<tr>
<td>Long-term Investments</td>
<td>500</td>
<td>421</td>
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<tr>
<td></td>
<td>7.8%</td>
<td>7%</td>
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<tr>
<td>Fixed Assets</td>
<td>1,084</td>
<td>1,220</td>
</tr>
<tr>
<td></td>
<td>17%</td>
<td>25%</td>
</tr>
<tr>
<td>Total Assets</td>
<td>5,220</td>
<td>5,788</td>
</tr>
<tr>
<td></td>
<td>100%</td>
<td>100%</td>
</tr>
<tr>
<td>LT Debt</td>
<td>89</td>
<td>144</td>
</tr>
<tr>
<td></td>
<td>1.5%</td>
<td>3.5%</td>
</tr>
<tr>
<td>Shareholders' Equity</td>
<td>3,104</td>
<td>2,758</td>
</tr>
<tr>
<td></td>
<td>50%</td>
<td>50%</td>
</tr>
<tr>
<td>EBITDA</td>
<td>646</td>
<td>555</td>
</tr>
</tbody>
</table>

*EBITDA=operating income + depreciation & amortization expenses*
Thank You

http://www.mpi.com.tw